

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Change the packaging specification	26/AUG/21	KATE	CHERRY
2		Corrected the terminal material	29/OCT/21	KATE	CHERRY

Electrical

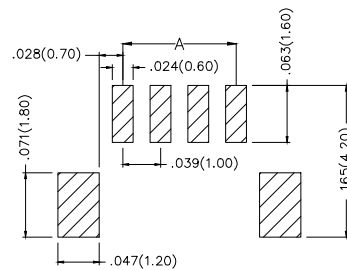
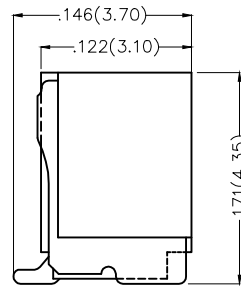
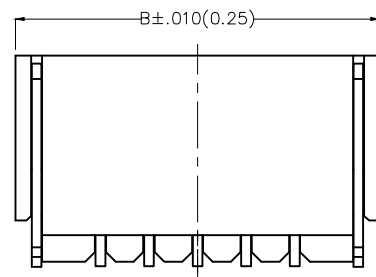
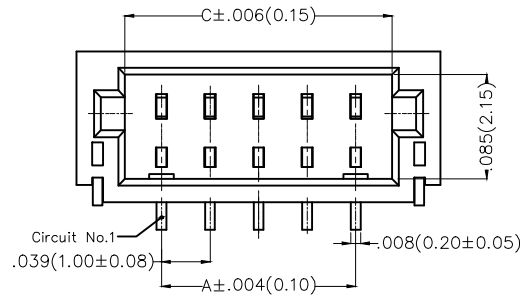
Current Rating: 1A AC(rms)/DC
Voltage Rating: 50V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 100 MΩ MIN
Withstanding Voltage: 500V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA9T(UL 94V-0)

Contact Pin: Phosphor bronze/ Tin plated

Solder Tab: Copper alloy/ Tin plated



Recommended P.C.Board Layout

Ordering Information

FWF 100 02 — S XX S 2 4 W5 M
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 100—Pitch1.0mm	3	Distinction No. 02	4	Row Option S—Single Row	5	Circuits XX	6	Entry Angle S—180° Vertical
7	Plating 2—Tin Plated	8	Material—Resin 4—PA9T	9	Color—Resin W5—White	10	Packaging M—Reel				

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF10002-SXXS24W5M	ITEM NO. FWF10002	 Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X'±2°	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		REV 2	SHEET NO. 1/3
		X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5°	CHERRY	28/JUN/13				

TXGA
Leader Of Industry

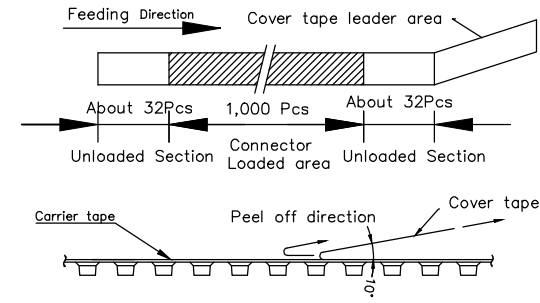
REV 2 SHEET NO. 1/3

1					2					3					4					5					6		7		8		
																				REV		LOCATIONS		DESCRIPTION		DATE		REVISER		APPD	

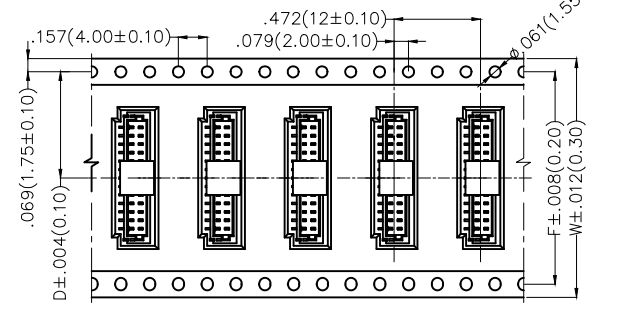
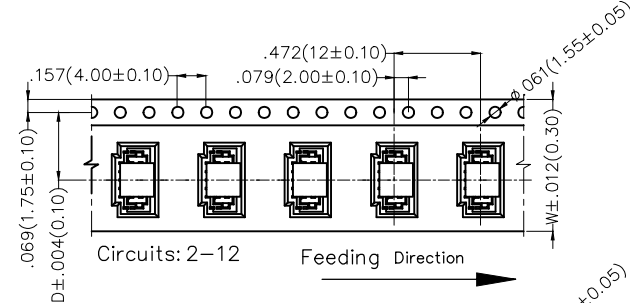
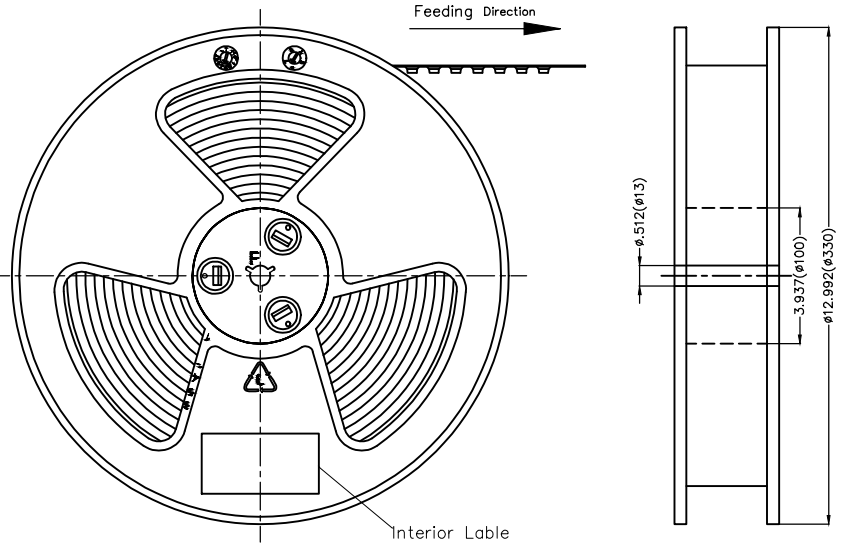
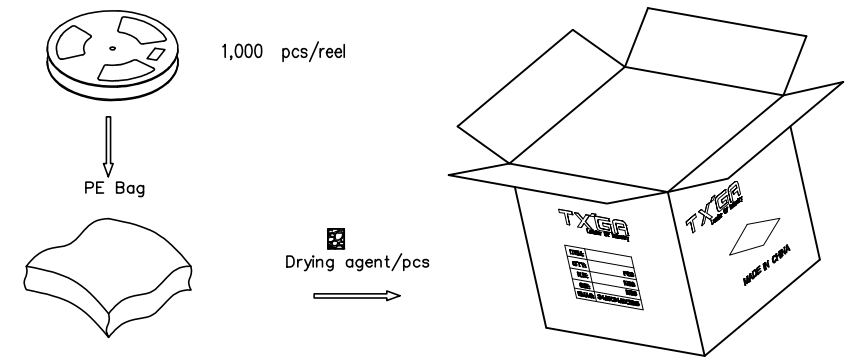
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Note:

1. 10 sprocket hole cumulative tolerance±0.2
2. Carrier camber is within 1.0mm in 250mm
3. Material: White Conductive polystyrene Alloy 100% recyclable
4. All dimensions meet EIA-481-3 requirements
5. Peel off force of cover tape&carrier tape: 20g~130g(0.2N~1.3N)
6. Component load per 13" reel: 1,000 pcs



Circuits (n)	Dimensions(in/mm)		
	D	W	F
2~5	.295(7.50)	.630(16.00)	—
6~12	.453(11.50)	.945(24.00)	—
13~16	.561(14.25)	1.260(32.00)	1.122(28.50)
17~20	.797(20.25)	1.732(44.00)	1.594(40.50)



 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF10002-SXXS24W5M	ITEM NO. FWF10002	 Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X'±2°	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 1.0mm 180° Vertical (SMT)		REV 2	SHEET NO. 3/3
		X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S,Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5°	CHERRY	28/JUN/13				